



"PRECISION, INNOVATION & DEDICATION. EVERY MISSION, EVERY TIME."



Mission Statement

Advanced Mission Partners is committed to operating as a trusted strategic partner focused on the design, manufacturing, and testing of high-quality electronic subassemblies and systems for all applications.

Overview

Advanced Mission Partners is dedicated to delivering low-cost, high reliability solutions to our customers. Our infrastructure is designed to support both highly complex mission-critical hardware as well as quick turn R&D efforts. The manufacturing team leveraged over 150 years of combined experience and lessons learned to build a 32,000 sq. ft. facility. Our technical staff and leadership are dedicated to delivering on customer commitments while maintaining a strong focus on reducing waste and inefficiency.

Core Capabilities

Engineering

- Systems Engineering
 - Requirements Development and Management
 - Verification and Validation
- Electrical, Electronic and Electromechanical (EEE) Parts Selection, Procurement and Analysis
- Electrical and Power Systems Design
- Design For Manufacturability Services (DFM)
- Flight and Ground Systems Integration
- EGSE/STE Design, Development and Maintenance

Electronics Manufacturing

- Manufacturing of Circuit Card Assembly (CCA) size up to 20" x 20"
- Quick turnaround & Rapid prototyping
- Component placements as small as 0.008" X 0.004" with an accuracy of ± 1.4 mil
- High-resolution vision system capable of measuring BGA balls as small as 4 mil in diameter with a 10 mil pitch
- Supportability of 224 unique components in one set up (based on component size) and 30 matrix tray components
- Intelligent electronic feeders
- Traceability from the Circuit Card Assembly (CCA) back to the original component manufacturer

Program Management

- Concept to delivery PM services
- Expert planning, execution, and oversight
- Proactive risk analysis and mitigation
- Consistent and timely communication
- On time delivery and budget tracking
- Strategic resource monitoring and allocation
- Stakeholder engagement and relationship management

Machine Specs

Machine	Capabilities
 <p>SQ3000 Multi Function 3D AOI</p>	<ul style="list-style-type: none"> • 3D AOI, SPI and PWB CMM capability • High-Resolution sensor capable of inspecting component sizes as small as .008" x .004" • Gage R&R accuracy <10% @ ±3σ (±80 μm process tolerance) • Provides 3D measurements for solder, component height, and component body/lead coplanarity
 <p>JUKI RS-1RXL Pick and Place Equipment</p>	<ul style="list-style-type: none"> • Support for PCB sizes up to 25" x 25" • Placement accuracy ± 1.37 mils (35 μm) • 27mm vision camera for BGA and leaded component placement • BGA ball size 4 mils minimum • BGA ball pitch 10 mils minimum • QFP lead size 8 mils x 5 mils minimum • QFP lead pitch 12 mils minimum • Smallest component size 008004 Imperial (0201 Metric) • Capacity for 224 unique components (8mm reels) and 30 matrix trays • Combined throughput of 58,000 CPH per IPC9850 • Intelligent feeders with full traceability of component placements
 <p>Heller 1913 MK5 Reflow Oven</p>	<ul style="list-style-type: none"> • 26 Independent temperature-controlled heating zones • 3 Top side cooling zones • Zone temperature stability ± 1C • Center board support • KIC SPS wireless smart profiler • KIC PROBOT automatic profile capture • Oven air temperature recorded for each CCA real time. Temperatures are compared to previous known good profiles to validate successful reflow.

Past Performance & Teammates



Company Details

UEI: RZJNZDE9K255
 Primary NAICS Code:
 334418
 Cage Code: 9TX45

Registrations/Certifications

- IPC-600
- IPC-610
- IPC-620
- IPC-7711/7721
- J-STD-001 w/ Space Addendum

Awards/Recognition

- Women Owned Small Business Certified
- Culture Excellence Awards:
 - Work-Life Flexibility
 - Compensation and Benefits

